



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP171P H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001070988						
<b>Package</b>		PG-SOT223-4-21		<b>Weight*</b>		113.69 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.077	0.07		679	
	non noble metal	tin	7440-31-5	0.020	0.02		175	
	inorganic material	silicon	7440-21-3	0.875	0.77	0.86	7700	8554
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1338	
	non noble metal	copper	7440-50-8	50.489	44.41	44.59	444094	445967
wire	non noble metal	copper	7440-50-8	0.091	0.08	0.08	798	798
encapsulation	organic material	carbon black	1333-86-4	0.599	0.53		5273	
	plastics	epoxy resin	-	8.992	7.91		79094	
	inorganic material	silicondioxide	60676-86-0	50.356	44.29	52.73	442925	527292
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12877	12877
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4512	4512
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com